

REMARKS

1. Claims 1-25 are pending in the application. Of these claims, claims 1-10 and 13-19, 22 and 23 stand rejected and claims 11, 12, 20, 21, 24 and 25 stand objected to. This communication amends claims 8, 12, 13, 18, 21 and 22 and cancels claims 1-7, 9-11, 15-17, 19, 20 and 24. Reconsideration of this application is respectfully requested.

2. It is noted that objected to claims 11, 12, 20, 21, 24 and 25 contain allowable subject matter.

3. The Office Action states that the drawings, particularly FIGS. 3a-6b, do not comply with 37 CFR 1.121(d) because they do not clearly show the invention. The Office Action further states that FIGS. 1-2b should be designated with legend such as "Prior Art."

In response, FIGS. 1-2b have been amended to include the legend -- Prior Art --; and replacement sheets for FIGS. 3a-6b of the drawings have been provided, which are clean copies of the figures, and which show the figures with greater clarity.

4. Claim 13 stands rejected under 35 USC 112, second paragraph, as being indefinite because the term "the outer rectilinear portion" and the term "the sawtooth pattern" lack proper antecedents. In response, claim 13 and claim 8, from which claim 13 depends, have been amended to provide proper antecedent basis for these features.

5. Claims 1, 5, 8 and 15 stand rejected under 35 USC 102(b) as being anticipated by U.S. Patent 6,100,589 to Tanaka.

Claims 1, 5 and 15 have been cancelled herein.

Claim 8 has been amended to recite the allowable subject matter recited in cancelled claim 11; to recite a method of providing a test pad for a multilayer semiconductor device.

In view of the foregoing, withdrawal of this rejection is respectfully requested.

6. Claims 2-4, 6, 7 and 14 stand rejected under 35 USC 103(a) as being unpatentable over Tanaka in view of "the cited case law."

Claims 2-4, 6 and 7 have been cancelled herein.

Claim 14 depends from amended claim 8 which now contains the allowable subject matter of claim 11.

In view of the foregoing, withdrawal of this rejection is respectfully requested.

7. Claims 9-10, 16 and 17 stand rejected under 35 USC 103(a) as being unpatentable over Tanaka as applied to claims 1 and 5, and further in view of U.S. Patent 5,874,356 to Chen et al.

This rejection is no longer applicable as claims 9-10, 16 and 17 have been cancelled herein. Accordingly, withdrawal of this rejection is respectfully requested.

8. Claims 18, 19, 22 and 23 stand rejected under 35 USC 103(a) as being unpatentable over Tanaka in view of U.S. Publication 2003/0047794 A1.

Claim 18 has been amended to recite the allowable subject matter recited in cancelled claim 20.

Claim 19 has been cancelled.

Claim 22 has been amended to recite the allowable subject matter recited in cancelled claim 24.

Claim 23 depends from claim 22 which now contains the allowable subject matter of claim 24.

In view of the foregoing, withdrawal of this rejection is respectfully requested.

9. Favorable reconsideration of this application is respectfully requested as it is believed that all outstanding issues have been addressed herein and, further, that claims 8, 12-14, 18, 21-23 and 25 are in condition for allowance, early notification of which is earnestly solicited. Should there be any questions or matters whose resolution may be advanced by a telephone call, the examiner is cordially invited to contact applicants' undersigned attorney at his number listed below.

10. The Commissioner is hereby authorized to charge payment of any additional filing fees required under 37 CFR 1.16 and any patent application processing fees under 37 CFR 1.17, which are associated with this communication, or credit any overpayment to Deposit Account No. 50-2061.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "J.M. Chamberlain", is written over a horizontal line.

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